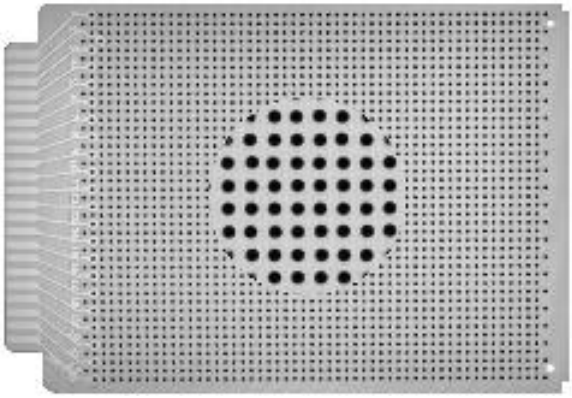
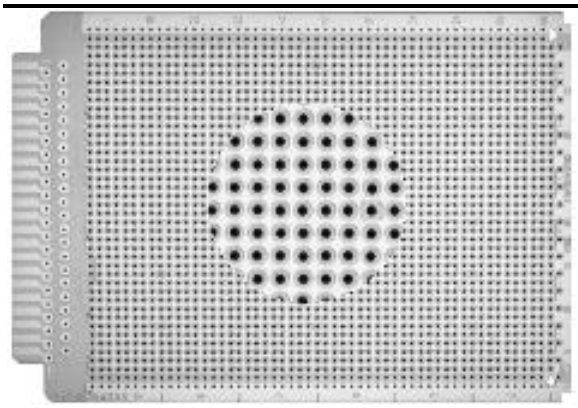


3662 4.5" x 6.5"

Circuit Pattern:	Contacts Only
Contacts:	22/44 @ .156 Ctrs, Ni/Gold
Width/Thick:	6.50"/.062"
Height:	4.50"
16-Pin DIP Capacity:	50
Material:	CEM-1.
Wire-Wrap Terminals:	T44, T46, T49, T68
Wire-Wrap Socket Pins:	R32
Solder Connector:	R644
Extender:	3690
Rec. Card Cage:	Series 13
Wire-Wrap Connector:	R644-3
Hole Diameter:	.042"

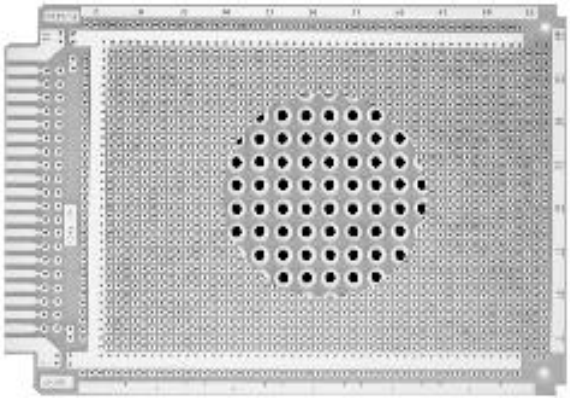
- *Unrestricted component place ment over entire board surface*
- *Layout paper and instructions included*
- *Row and column legend provided*



3662A6 4.5" x 6.5"

Circuit Pattern:	Ground Plane
Contacts:	22/44 @ .156" Ctrs, Ni/Gold
Width/Thick:	6.50"/.062"
Height:	4.50"
16-Pin DIP Capacity:	90
Material:	CEM-1 .
Wire-Wrap Terminals:	T44, T46, T49, T68
Wire-Wrap Socket Pins	R32
Solder Connector:	R644
Extender:	3690
Rec. Card Cage:	Series 13
Wire-Wrap Connector:	R644-3
Hole Diameter:	.042"

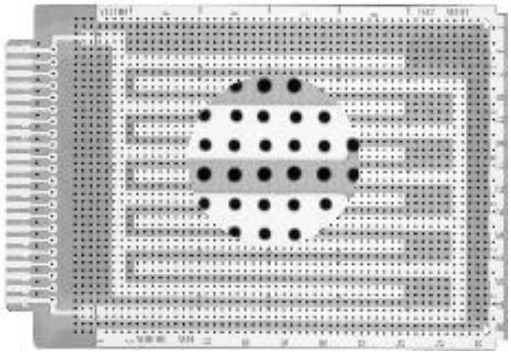
- *0.085" diameter clearance area around holes*
- *Ground plane on component side; wiring side has contacts only*
- *To commit wire-wrap pins to ground planes, use Vector T124 solder washers, available separately*
- *Plane surface is solder-coated for user convenience*
- *Layout paper and instructions included*
- *Row and column legend provided*



3662-9 4.5" x 6.5"

Circuit Pattern:	Pad-Per-Hole
Contacts:	22/44 @ .156" Ctrs, Ni/Gold
Width/Thick:	6.50"/.062"
Height:	4.50"
16-Pin DIP Capacity:	48
Material:	FR4 Epoxy Glass
Wire-Wrap Terminals:	T44, T46, T49, T68
Wire-Wrap Socket Pins	R32
Solder Connector:	R644
Extender:	3690
Rec. Card Cage:	Series 13
Wire-Wrap Connector:	R644-3
Hole Diameter:	.042"

- *0.080" diameter, isolated solder pad around holes, both sides*
- *Pad and bus surfaces solder-coated for quick, convenient soldering*
- *Row and column legends provided*
- *Layout paper and instructions included*



3682-2 4.5" x 6.5"

Circuit Pattern:	Interleaved Buses
Contacts:	22/44 @ .156" Ctrs, Ni/Gold
Width/Thick:	6.50"/.062"
Height:	4.50"
16-Pin DIP Capacity:	24
Material:	CEM-1
Wire-Wrap Terminals:	T44, T46, T49, T68
Wire-Wrap Socket Pins:	R32
Solder Connector:	R644
Extender:	3690
Rec. Card Cage:	Series 13
Wire-Wrap Connector:	R644-3
Hole Diameter:	.042"

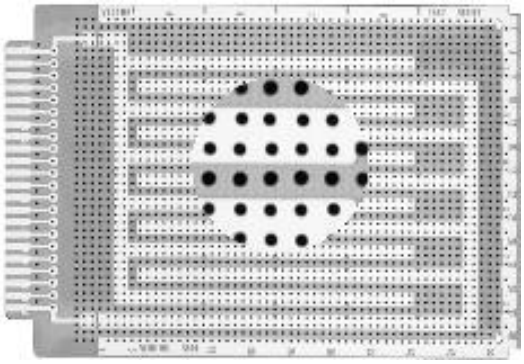
- *Bus pattern on wiring side, solder-coated for user convenience*
- *Bus outline traced on component side to facilitate component placement*
- *Mounts DIPs with 0.3", 0.4" and 0.9" lead spacing*
- *Unclad test point area at top of board*
- *Layout paper and instructions included*
- *Row and column legends provided*

Note: Same as 3682-4 but without Ground Plane

3682-4 4.5" x 6.5"

Circuit Pattern:	Interleaved Bus/ Ground Plane
Contacts:	22/44 @ .156" Ctrs, Ni/Gold
Width/Thick:	6.50"/.062"
Height:	4.50"
16-Pin DIP Capacity:	24
Material:	CEM-1
Wire-Wrap Terminals:	T44, T46, T49, T68
Wire-Wrap Socket Pins:	R32
Solder Connector:	R644
Extender:	3690
Rec. Card Cage:	Series 13
Wire-Wrap Connector:	R644-3
Hole Diameter:	.042"

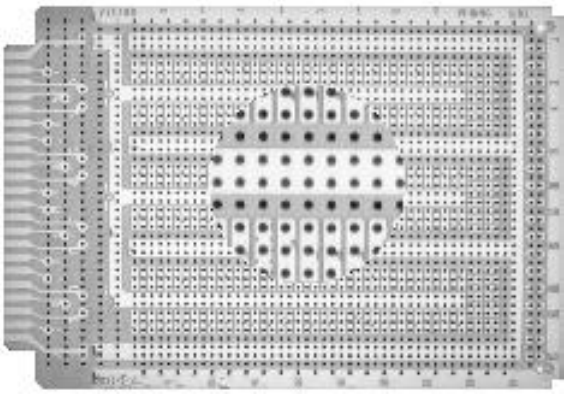
- *Power bus in rows across component side; overall ground plane on wiring side*
- *0.085" etched clearance area around each hole on ground plane side*
- *Bus and plane surfaces solder coated for user convenience*
- *To commit wire-wrap pins to ground planes, use Vector T124 solder washers, available separately*
- *Layout paper and instructions included*
- *Row and column legends provided*



3677-2 4.5" x 6.5"

Circuit Pattern:	3-Hole Solder Pad
Contacts:	22/44 @ .156" Ctrs. Ni/Gold
Width/Thick:	6.50"/.062"
Height:	4.50"
16-Pin DIP Capacity:	12
Material:	CEM-1
Wire-Wrap Terminals:	T44, T46, T49, T68
Wire-Wrap Socket Pins:	R32
Solder Connector:	R644
Extender:	3690
Rec. Card Cage:	Series 13
Wire-Wrap Connector:	R644-3
Hole Diameter:	.042"

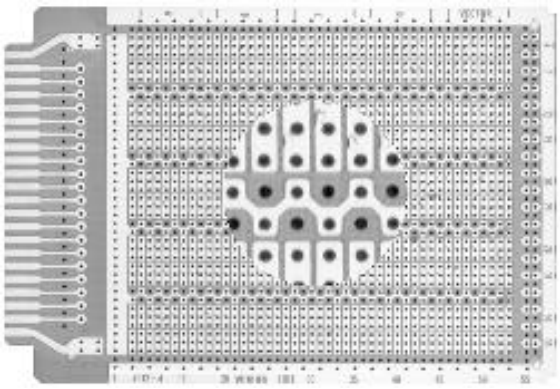
- *3-hole solder pads (0.28" x 0.080") for interconnecting multiple component leads*
- *Voltage/ground buses interleaved between pad areas on wiring side*
- *Row and column legends provided*
- *Test point area, with solder pads around holes, provided along back edge of board*
- *Layout paper and instructions included*



4112-4 4.5" x 6.5"

Circuit Pattern:	3-Hole Solder Pad
Contacts:	22/44 @ .156" Ctrs, Ni/Gold
Width/Thick:	6.50"/.062"
Height:	4.50"
16-Pin DIP Capacity:	25
Material:	CEM-1
Wire-Wrap Terminals:	T44, T46, T49, T68
Wire-Wrap Socket Pins:	R32
Solder Connector:	R644
Extender:	3690
Rec. Card Cage:	Series 13
Wire-Wrap Connector:	R644-3
Hole Diameter:	.042"

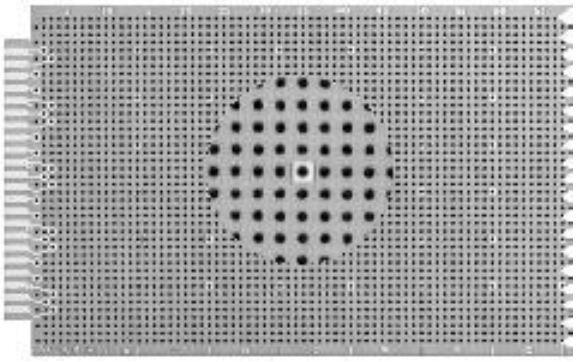
- *Continuous ground plane on component side with 0.085" clearance pad around each hole*
- *3-hole solder pads (0.28 x 0.080") for interconnecting multiple component leads*
- *Row and column legends provided*
- *Layout paper and instructions included*



3662-2 4.5" x 9.6"

Circuit Pattern:	Contacts Only
Contacts:	22/44 @ .156" Ctrs, Ni/Gold
Width/Thick:	9.60"/.062"
Height:	4.50"
16-Pin DIP Capacity:	90
Material:	CEM-1
Wire-Wrap Terminals:	T44, T46, T49, T68
Wire-Wrap Socket Pins:	R32
Solder Connector:	R644
Extender:	3690-6
Rec. Card Cage:	Series 14
Wire-Wrap Connector:	R644-3
Hole Diameter:	.042"

- *Unrestricted component placement over entire board surface*
- *Row and column legends provided*
- *Layout paper and instructions included*



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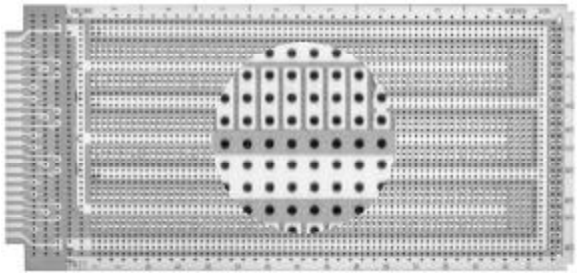
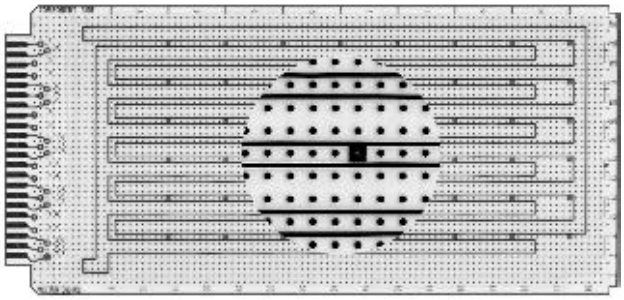


3677 4.5" x 9.6"

Circuit Pattern:	3-Hole Solder Pad
Contacts:	22/44 @ .156" Ctrs, Ni/Gold
Width/Thick:	9.60"/.062"
Height:	4.50"
16-Pin DIP Capacity:	21
Material:	CEM-1
Wire-Wrap Terminals:	T44, T46, T49, T68
Wire-Wrap Socket Pins	R32
Solder Connector:	R644
Extender:	3690
Rec. Card Cage:	Series 14
Wire-Wrap Connector:	R644-3
Hole Diameter:	.042"

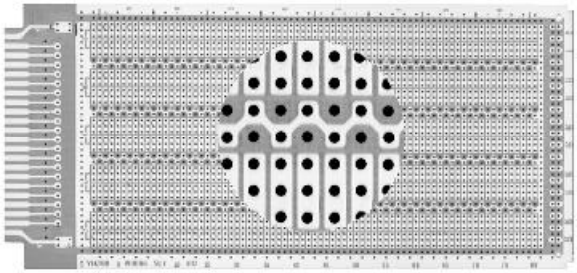
- *3-hole solder pads (0.28" x 0.080") for interconnecting multiple component leads*
- *Row and column legends provided*
- *Layout paper and instructions included*



3682 4.5" x 9.6"

Circuit Pattern:	Interleaved Buses
Contacts:	22/44 @ .156 Ctrs, Ni/Gold
Width/Thick:	9.60"/.062"
Height:	4.50"
16-Pin DIP Capacity:	48
Material:	CEM-1
Wire-Wrap Terminals:	T44, T46, T49, T68
Wire-Wrap Socket Pins	R32
Solder Connector:	R644
Extender:	3690-6
Rec. Card Cage:	Series 13
Wire-Wrap Connector:	R644-3
Hole Diameter:	.042"

- *Etched bus pattern on wiring side, solder-coated for user convenience*
- *Bus outlines traced on component side*
- *Mounts DIPs with 0.3", 0.4" and 0.9" lead spacings*
- *Layout paper and instructions included*
- *Row and column legends provided*



4112 4.5" x 9.6"

Circuit Pattern:	3-Hole Solder Pad
Contacts:	22/44 @ .156" Ctrs, Ni/Gold
Width/Thick:	9.60"/.062"
Height:	4.50"
16-Pin DIP Capacity:	40
Material:	FR4 Epoxy Glass
Wire-Wrap Terminals:	T44, T46, T49, T68
Wire-Wrap Socket Pins:	R32
Solder Connector:	R644
Extender:	3690-6
Rec. Card Cage:	Series 13
Wire-Wrap Connector:	R644-3
Hole Diameter:	.042"

- *Zig-zag bus pattern on wiring side provides access to voltage or ground at alternating hole positions*
- *3-hole solder pads (0.28" x 0.080") for interconnecting multiple component leads*
- *Continuous ground plane on component side with 0.085" etched clearance area around each hole*
- *Layout paper and instructions included*
- *Row and column legends provided*

Общество с ограниченной ответственностью «МосЧип» ИНН 7719860671 / КПП 771901001
Адрес: 105318, г.Москва, ул.Щербаковская д.3, офис 1107

Данный компонент на территории Российской Федерации

Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

http://moschip.ru/get-element

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Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

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